This listing of claims will replace all prior versions, and listings, of claims in the subject patent application:

Listing of Claims:

1-21. (Canceled)

22. (Previously presented) A method for the manufacture of a housing having a housing portion adjacent a printed circuit board for accommodating electronic functional elements (2), comprising:

forming a screening seal (8; 8') to fill a gap between said housing part and said printed circuit board, said seal being made from an electrically conductive elastic plastic material, said electrically conductive elastic plastic material including a silicon polymer, said forming including ejecting said polymer in a pasty initial state with a pressure nozzle and passing said pressure nozzle over one of said housing portions that is to be sealed, so that said polymer is deposited directly on said one of said housing portion (3a) and said printed circuit board, to form said screening seal with a predetermined profile (8; 8') without a molding tool; and allowing said screening seal to cure on said one of said housing portion and printed circuit board wherein said screening seal adheres to a surface of said one of said housing portion and said printed circuit board in such a manner that the screening seal maintains its electrical and sealing characteristics even after repeated opening of the housing.

23. (Previously presented) The method according to claim 22, further comprising forming said screening seal by passing said nozzle several times at least over predetermined regions of said one of said housing portion and said printed circuit board to form said screening seal with said

profile having a predetermined cross-section.

24. (Previously presented) The method according to claim 22, wherein during said passing said nozzle repeatedly over the predetermined regions, different elastic materials are applied, at least one of said different elastic materials being a conductive material.

25. (Previously presented) The method according to 22, wherein said forming of said screening seal is accomplished in several layers at least in some regions, each layer being formed directly on the layer lying beneath it and joined by adhesion thereto.

26. (Previously presented) The method according to claim 22, wherein said forming of said screening seal includes forming a first layer made of a material that is very elastic but is at most only slightly conductive and forming another layer made of another material which is only slightly elastic, but is very conductive.

27. (Previously presented) The method according to claim 22 further comprising forming said predetermined profile of several strands of material, each said strand having a lip-shaped cross-section.

28. (Previously presented) The method according to claim 22 further comprising forming said profile in several strands of material wherein said strands cooperate to form a hollow section.

29. (Previously presented) The method of claim 22 further comprising forming said screening seal in several layers wherein at least one of said of layers is formed of a non-conductive

material.

30. (Previously presented) The method of claim 22 wherein said polymer is a polymer that dries fast in air.

31. (Previously presented) The method of claim 22 further comprising forming said screening seal in several layers, some layers which differ in at least one of compressibility, elasticity, flexibility and hardness.

32. (Previously presented) The method of claim 22, wherein said portions are mated in a tongue-and-groove arrangement further comprising forming said screening seal in parallel with said tongue-and-groove arrangement.

33. (Previously presented) The method of claim 22 further comprising forming said screening seal inward of said tongue-and-groove arrangement.

34. (Previously presented) A method for the manufacture of a housing having a housing part and an electrical printed circuit board, comprising:

forming a screening seal (8; 8') to fill a gap between said housing part and said printer circuit board, said seal being made from an elastic and electrically conductive plastic material, said electrically conductive plastic material including a silicon polymer, said forming including ejecting said polymer in a pasty initial state with a pressure nozzle and passing said pressure nozzle over said electrical printed circuit board that is to be sealed, so that said polymer is deposited directly on said electrical printed circuit board to form said screening seal with a

predetermined profile (8; 8') without a molding tool; and allowing said screening seal to cure on said electrical printed circuit board wherein said screening seal adheres to a surface of said electrical printed circuit board in such a manner that the screening seal maintains its electrical and sealing characteristics even after repeated opening of the housing.

35. (Previously presented) The method according to claim 34, further comprising forming said screening seal by passing said nozzle several times at least over predetermined regions of said one of said housing portion and printed circuit board to form said screening seal with said profile having a predetermined cross-section.

36. (Previously presented) The method according to claim 34, wherein during said passing said nozzle repeatedly over the predetermined regions, different elastic materials are applied, at least one of said different elastic materials being a conductive material.

37. (Previously presented) The method according to 34, wherein said forming of said screening seal is accomplished in several layers at least in some regions, each layer being formed directly on the layer lying beneath it and joined by adhesion thereto.

38. (Previously presented) The method according to claim 34, wherein said forming of said screening seal includes forming a first layer made of a material that is very elastic but is at most only slightly conductive and forming another layer made of another material which is only slightly elastic, but is very conductive.

39. (Previously presented) The method according to claim 34 further comprising forming said

predetermined profile of several strands of material, each said strand having a lip-shaped cross-section.

40. (Previously presented) The method according to claim 34 further comprising forming said profile in several strands of material wherein said strands cooperate to form a hollow section.

41. (Previously presented) The method of claim 34 further comprising forming said screening seal in several layers wherein at least one of said of layers is formed of a non-conductive material.

42. (Previously presented) The method of claim 34 further comprising forming said screening seal in several layers, some layers which differ in at least one of compressibility, elasticity, flexibility and hardness.

43. (Previously presented) The method of claim 34, wherein said portions are mated in a tongue-and-groove arrangement further comprising forming said screening seal in parallel with said tongue-and-groove arrangement.

44. (Previously presented) The method of claim 34 further comprising forming said screening seal inward of said tongue-and-groove arrangement.

45 (Previously presented) A method for the manufacture of a housing having a housing part and an electrical printed circuit board, comprising:

forming a screening seal (8; 8') to fill a gap between said housing part and said printer

circuit board, said seal being made from an elastic and electrically conductive plastic material, said electrically conductive plastic material including a silicon polymer that dries rapidly in air, said forming including ejecting said polymer in a pasty initial state with a pressure nozzle, and passing said pressure nozzle over said electrical printed circuit board that is to be sealed, so that said polymer is deposited directly on said electrical printed circuit board to form said screening seal with a predetermined profile (8; 8') without a molding tool; and allowing said screening seal to cure on said electrical printed circuit board wherein said screening seal adheres to a surface of said electrical printed circuit board in such a manner that the screening seal maintains its electrical and sealing characteristics even after repeated opening of the housing.

46-50. (Canceled)

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